

C1 fluid comprising an ozone-containing gas and ultra pure water are sprayed onto substrates or semiconductor wafers in a treating chamber filled with ozone gas."

**IN THE CLAIMS:**

Please cancel claim 40 without prejudice.

Please amend claim 27 as follows:

Sub E1  
C2  
27. (Twice Amended) A method for removing organic contaminants from a substrate, comprising the steps of:

contacting at least one side of said substrate with a liquid comprising water, ozone and an additive acting as a scavenger, wherein the proportion of said additive in said liquid is less than

1% molar weight of said liquid; and

maintaining said liquid at a temperature less than the boiling point of said liquid.

Please add the following claims 51-60:

Sub E2  
C3  
--51. A method for removing organic contaminants from a substrate, comprising the steps of:

contacting at least one side of said substrate with a liquid comprising water, ozone and an additive acting as a scavenger, wherein said liquid is comprised substantially of water; and

maintaining said liquid at a temperature less than the boiling point of said liquid.

25  
32. A method as recited in claim <sup>21</sup>51, wherein the proportion of said additive in said liquid is less than 1% molar weight of said liquid.

<sup>26</sup>/~~53~~. A method according to claim <sup>25</sup>/~~52~~, wherein the proportion of said additive in said liquid is less than 0.1% molar weight of said liquid.

<sup>27</sup>/~~54~~. A method as recited in claim <sup>29</sup>/~~51~~, wherein the temperature of said liquid is between 60°C and 80°C.

<sup>28</sup>/~~55~~. A method as recited in claim <sup>29</sup>/~~51~~, wherein said liquid is subjected to megasone agitation.

C <sup>29</sup>/~~56~~. A method as recited in claim <sup>29</sup>/~~51~~, wherein the ozone is bubbled through the liquid.

<sup>30</sup>/~~57~~. A method as recited in claim <sup>29</sup>/~~51~~, wherein said additive is acting as OH radical scavenger.

<sup>31</sup>/~~58~~. A method as recited in claim <sup>29</sup>/~~51~~, further comprising the step of rinsing said substrate with a solution.

<sup>32</sup>/~~59~~. A method as recited in claim <sup>31</sup>/~~58~~, wherein said solution comprises de-ionised water.